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#### REMARKS/ARGUMENTS

Claims 1-10 are pending in this application. The Examiner has withdrawn claim 9 from consideration. By this Amendment, Applicant AMENDS claims 1, 5, and 10.

Applicant respectfully submits that claim 1 is generic. Since claim 9 depends upon generic claim 1, Applicant respectfully requests that the Examiner rejoin and allow claim 9 when claim 1 is allowed.

Claims 1-7 and 10 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Kubota et al. (U.S. 5,644,107). Claim 8 was rejected under 35 U.S.C. 103(a) as being unpatentable over AAPA and Kubota et al., and further in view of Marusawa et al. (JP 9-294006). Applicant respectfully traverses the rejection of claims 1-8 and 10.

Claim 1 has been amended to recite:

"A center-electrode assembly comprising:  
a ferrite;  
center-electrode patterns and insulating films deposited on the top surface of the ferrite;  
a conductive pattern formed on the bottom surface of the ferrite;  
and  
connecting electrodes directly formed on sides of the ferrite;  
wherein  
the connecting electrodes electrically connect the center-electrode patterns and the conductive pattern; and  
**said connecting electrodes, said center-electrode pattern and said conductive pattern are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material, and an applied paste conductive material formed directly on the sides, on the top surface and on the bottom surface, respectively, of the ferrite.**" (emphasis added)

Claim 5 has been amended to recite:

"A method for manufacturing a center-electrode assembly comprising the steps of:  
forming through-holes in a ferrite mother board;  
alternately depositing a center-electrode pattern and an insulating

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**film on the top surface of the ferrite mother board, the center-electrode pattern is formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method;**

**forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method;**

**cutting a center-electrode assembly from the ferrite mother board by cutting the ferrite mother board at intervals of a predetermined size; and**

**forming connecting electrodes in the through-holes in the center electrode assembly by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method and a conductive paste applying method to electrically connect the center-electrode patterns formed on the top surface and the conductive pattern formed on the back surface." (emphasis added)**

Applicant's claim 1 recites the feature of "said connecting electrodes, said center-electrode pattern and said conductive pattern are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material, and an applied paste conductive material formed directly on the sides, on the top surface and on the bottom surface, respectively, of the ferrite." Applicant's claim 5 recites the features of "the center-electrode pattern is formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" and "forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method." Applicant's claim 10 recites features that are similar to the features recited in Applicant's claim 1, including the above emphasized features. With the improved features of claims 1, 5, and 10, Applicant has been able to provide a center-electrode assembly that has stable electrical characteristics, is easily handled, and is suitable for mass production and a manufacturing method therefore

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(see, for example, the paragraph bridging pages 2 and 3 of the originally filed Specification).

The first full paragraph on page 2 of the originally filed Specification states, "The conventional center-electrodes 271, 272 and 273 are made by punching a thin metallic plate." That is, neither the center-electrode pattern nor the conductive pattern are formed by a plating method, a printing method, a sputtering method, a vapor deposition method, or a conductive paste applying method. Thus, Applicant respectfully submits that AAPA fails to teach or suggest the feature of "said connecting electrodes, said center-electrode pattern and said conductive pattern are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material, and an applied paste conductive material formed directly on the sides, on the top surface and on the bottom surface, respectively, of the ferrite" as recited in Applicant's claims 1 and 10 or the features of "the center-electrode pattern is formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" and "forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" as recited in Applicant's claim 5.

The Examiner has relied upon Kadota et al. to allegedly cure various deficiencies in AAPA. However, Kadota et al. fails to teach or suggests the use of center-electrode patterns or a conductive pattern and certainly fails to teach or suggest how center-electrode patterns or conductive pattern should be formed. Thus, Applicant respectfully submits that Kadota et al. fails to teach or suggest the feature of "said connecting electrodes, said center-electrode pattern and said conductive pattern are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material, and an applied paste conductive material formed directly on the sides, on the top surface and on the bottom

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surface, respectively, of the ferrite" as recited in Applicant's claims 1 and 10 or the features of "the center-electrode pattern is formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" and "forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" as recited in Applicant's claim 5.

Accordingly, Applicant respectfully requests reconsideration and withdrawal of the rejection of claims 1, 5, and 10 under 35 U.S.C. § 103(a) as being unpatentable over AAPA in view of Kubota et al.

The Examiner has relied upon Marusawa et al. to allegedly cure various deficiencies in the combination of AAPA and Kadota et al. However, Applicant respectfully submits that Marusawa et al. fails to teach or suggest the feature of "the center-electrode patterns and the conductive pattern are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material, and an applied paste conductive material formed directly on the top surface and the bottom surface, respectively, of the ferrite" in combination with the other features recited in Applicant's claims 1 and 10 or the features of "the center-electrode pattern is formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" and "forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method" in combination with the other features recited in Applicant's claim 5.

Accordingly, Applicant respectfully submits that AAPA, Kubota et al., and Marusawa et al., applied alone or in combination, fail to teach or suggest the unique combination and arrangement of elements recited in claims 1, 5, and 10 of the present application. Claims 2-4 and 6-8 depend upon claim 1 and are therefore allowable for at

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least the reasons that claim 1 is allowable. Applicant further submits that claim 1 is generic. Since claim 9 depends upon generic claim 1, Applicant respectfully requests that the Examiner rejoin and allow claim 9 when claim 1 is allowed.

In view of the foregoing amendments and remarks, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

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